TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN# 20120914002

Qualification of RFAB as an additional FAB Site Option for Select TPA2015D1YZH Devices in the LBC7 Process

Change Notification / Sample Request

Date: 9/19/2012
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20120914002
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TPA2015D1YZHT	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	PCN20120914002	**PCN Date:**	09/19/2012
Title:	Qualification of RFAB as an Additional FAB Site Option for Select TPA2015D1YZH Devices in the LBC7 Process		

Customer Contact:	PCN Manager	**Phone:**	+1(214)480-6037	**Dept:**	Quality Services

***Proposed 1st Ship Date:**	12/19/2012	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process

PCN Details

Description of Change:

This notification is to announce the qualification of RFAB as an additional FAB site option for select TPA2015D1YZH devices in the LBC7 Process.

Currently Qualified Site, process	**Additional Site, Process**
MIHO8, LBC7 Process	**RFAB, LBC7 Process**

The LBC7 process was previously qualified at RFAB on 3/3/2011. Qualification details are shown in the Qualification Data Section of this document.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Chip Site:

Current

Chip Site	Chip site code (20L)	Chip country code (21L)
MIHO8	MH8	JPN

New

Chip Site	Chip site code (20L)	Chip country code (21L)
RFAB	**RFB**	**USA**

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
MADE IN: Malaysia
2DC: 2Q:
MSL 2 /260C/1 YEAR | SEAL DT
MSL 1 /235C/UNLIM | 03/29/04
OPT:
ITEM: 39
LBL: 5A (L)TO:1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T)LOT: 3959047MLA
(4W) TKY(1T) 7523483SI2
(P)
(2P) REV: (V) 0033317
(20L) CSO: SHE (21L) CCO:USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

HPA01080YZHR	TPA2015D1YZHR	TPA2015D1YZHT

Qualification Data: Approval Date 3/3/2011

This qualification has been developed for the validation of this change. The qualification data will validate that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: TPIC2020RTQRG4

Wafer Fab Site:	RFAB	Metallization:	200Ti / 275TiN / 4500AlCu / 50Ti /300TiN
Wafer Fab Process:	LBC7	Wafer diameter:	300mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size		
		Lot#1	Lot#2	Lot#3
Life Test	1000/125C/Vmax	80/0	80/0	80/0
**Biased HAST	96/130C/85%/Vmax	80/0	-	-
**Autoclave 121C	96/121C/2 atm	80/0	-	-
**Temperature Cycle	1000/-65/150C	80/0	80/0	80/0
**High Temp. Storage Bake	150C (1000 Hrs)	80/0	-	-
ESD HBM	2000V	27/0	27/0	27/0
ESD CDM	750V	3/0	3/0	3/0
**Thermal Path Integrity	Per appropriate package level	12/0	12/0	12/0
Latch-up	(per JESD78)	6/0	6/0	6/0

** Preconditioning sequence: level 3 @ 260C peak +5/-0C

Qual Vehicle 2: TPS65830YFFR

Wafer Fab Site:	RFAB	Metallization:	200Ti / 275TiN / 4500AlCu / 50Ti /300TiN
Wafer Fab Process:	LBC7	Wafer diameter:	300mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size		
		Lot#1	Lot#2	Lot#3
**Unbiased HAST 130C/85%RH	96/-	38/0	38/0	38/0
**Temperature Cycle	-55/125C 1000 Cycles	39/0	38/0	37/0
ESD HBM	2000V	1/0	1/0	1/0
ESD CDM	500V	1/0	1/0	1/0
Latch-up	(per JESD78)	3/0	3/0	3/0

** Preconditioning sequence: level 1 @ 260C peak +5/-0C

Qual Vehicle 3: TPS65170RHDR

Wafer Fab Site:	RFAB	Metallization:	200Ti / 275TiN / 4500AlCu / 50Ti /300TiN
Wafer Fab Process:	LBC7	Wafer diameter:	300mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size		
		Lot#1	Lot#2	Lot#3
**Autoclave 121C	96/121C	38/0	38/0	38/0
**Temperature Cycle	-65/150C 1000 Cycles	39/0	39/0	39/0
**Thermal Shock	-65/150C 1000 Cycles	38/0	38/0	38/0
ESD HBM	2000V	3/0	3/0	3/0
ESD CDM	750V	3/0	3/0	3/0
Moisture Sensitivity, L2	Visual-1/40X	12/0	-	-
Moisture Sensitivity, L2	CSAM-1/100%	12/0	-	-
Moisture Sensitivity, L2	ThruSAM-1/100%	12/0	-	-
Moisture Sensitivity, L2	24/125C	12/0	-	-
Moisture Sensitivity, L2	168/85C / 60%	12/0	-	-
Moisture Sensitivity, L2	3/260C +5 / -0C	12/0	-	-
Moisture Sensitivity, L2	Visual-2/40X	12/0	-	-
Moisture Sensitivity, L2	Elec/25C	12/0	-	-
Moisture Sensitivity, L2	CSAM-2/100%	12/0	-	-
Moisture Sensitivity, L2	ThruSAM-2/100%	12/0	-	-

** Preconditioning sequence: level 3 @ 260C peak +5/-0C

Qual Vehicle 4: TLS2602DCARG4

Wafer Fab Site:	RFAB	Metallization:	200Ti / 275TiN / 4500AlCu / 50Ti /300TiN
Wafer Fab Process:	LBC7	Wafer diameter:	300mm

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size		
		Lot#1	Lot#2	Lot#3
Life Test, 125C	1000/125C Vmax	80/0	80/0	80/0
**Autoclave 121C	96/121C/2atm	80/0	-	-
**Temperature Cycle	-65/150C 1000 Cycles	39/0	39/0	39/0
ESD HBM	2000V	3/0	3/0	3/0
ESD CDM	750V	3/0	3/0	3/0
**Thermal Path Integrity, L3-260C	PRE VM	12/0	-	-
**Thermal Path Integrity, L3-260C	PRE SAM/CSAM/TSAM	12/0	-	-
**Thermal Path Integrity, L3-260C	Bake 24hr/125C	12/0	-	-
**Thermal Path Integrity, L3-260C	Soak 192hr/30C/60%	12/0	-	-
**Thermal Path Integrity, L3-260C	Reflow x3/260C +5/-0	12/0	-	-
**Thermal Path Integrity, L3-260C	POST VM	12/0	-	-
**Thermal Path Integrity, L3-260C	DC TEST	12/0	-	-
**Thermal Path Integrity, L3-260C	POST SAM/CSAM/TSAM	12/0	-	-
**Thermal Path Integrity, L3-260C	T/C 500cy/-65C/150C	12/0	-	-
**Thermal Path Integrity, L3-260C	POST TC SAM/CSAM/TSAM	12/0	-	-
Latch-up	CI/100mA	6/0	6/0	6/0
Latch-up	OV/1.5Vmax	6/0	6/0	6/0

** Preconditioning sequence: level 3 @ 260C peak +5/-0C

Qual Vehicle 5: TPS62620YFFR						
Wafer Fab Site:	RFAB	Metallization:	200Ti / 275TiN / 4500AlCu / 50Ti /300TiN			
Wafer Fab Process:	LBC7	Wafer diameter:	300mm			
Qualification:	☐ **Plan**	☒ **Test Results**				
Reliability Test		Conditions		Sample Size Lot#1	Lot#2	Lot#3
Temperature Cycle		-55/125C 1000 Cycles		80/0	80/0	80/0
ESD HBM		2000V		3/0	3/0	3/0
ESD CDM		750V		3/0	3/0	3/0
Signal Latch-up		before/85C		6/0	6/0	6/0
Signal Latch-up		after/85C		6/0	6/0	6/0

Qual Vehicle 6: TPA6140A2YFFR						
Wafer Fab Site:	RFAB	Metallization:	200Ti / 275TiN / 4500AlCu / 50Ti /300TiN			
Wafer Fab Process:	LBC7	Wafer diameter:	300mm			
Qualification:	☐ **Plan**	☒ **Test Results**				
Reliability Test		Conditions		Sample Size Lot#1	Lot#2	Lot#3
L/T 140C		480/-		38/0	39/0	40/0
**Unbiased HAST 130C/85%RH		96/-		39/0	39/0	39/0
**Temperature Cycle		-55/125C, 1000V		3/0	3/0	3/0
ESD HBM		2000V		3/0	3/0	3/0
ESD CDM		750V		3/0	3/0	3/0
Latch-up		Latchup		6/0	6/0	6/0
Latch-up		Elec Test		6/0	6/0	6/0
** Preconditioning sequence: level 3 @ 260C peak +5/-0C						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	**E-Mail**
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com